Fifth Batch of Engineering Students Heading for Japan

Yayasan Pelajaran MARA (YPM) has sent its fifth batch of students to Japan this year thanks to its collaboration with the Japan International Cooperation Agency under the Malaysia Higher Education Loan Fund Project (Help) which provides scholarships for engineering students. The scholarship is bond-free and is given to about 80 students each year to enable them to gain more knowledge in the field of engineering. Help scholarship candidates apply to enter the programme after their Sijil Pelajaran Malaysia (SPM) examinations. If accepted, they complete the first three years of study at Universiti Selangor before moving on to their final two years of study at a Japanese university. YPM consultant Tatsuo Konta stated that there were about 3,500 applications each year and students were shortlisted based on their SPM results, followed by a series of interviews. Once selected, the students would begin an intensive course to learn the Japanese language.

(Sourced from The Star)